Package Model Example

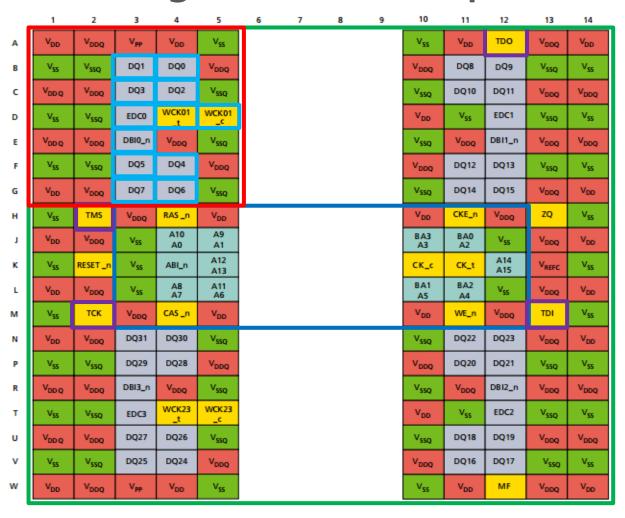
IBIS Interconnect Task Group

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Package Model Example



- [Interconnect Model]s
 - Red: ¼ package S-parameter
 - With VDDQ, VSS reference
 - Or no VDDQ, VSS reference
 - Lt. Blue: Uncoupled S-params, VSS ref
 - Blue: Lower speed Addr/Cmd
 - Fully coupled Spice subckt, VSS ref
 - Purple: Low speed JTAG
 - Uncoupled RLC
 - Green: PDN (no signals)
 - VDDQ, VDD, VSS reference
 - Spice coupled RLC
 - Green Option 2: Full pkg coupled RLC



Discussion

- With package symmetry, S-param models are re-useable up to 4 times
 - Same S-params, but different Terminal names
 - Is there an advantage to using [Interconnect Model] names and scoping outside a set?
- What can/should be included within a single [Interconnect Model Set]?
 - Should a set contain all Pins of a package?
 - Should there be a coupled set and uncoupled set?
 - What are overlapping [Interconnect Model]s useful for?



